Description

The VST25N2000 uses **Super Trench** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{DS(ON)}$ and Q_g. This device is ideal for high-frequency switching and synchronous rectification.

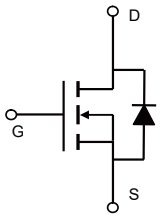
General Features

- V_{DS} =250V,I_D =15A
  $R_{DS(ON)}$=200mΩ (typical) @ V_{GS}=10V
- Excellent gate charge x $R_{DS(on)}$ product(FOM)
- Very low on-resistance $R_{DS(on)}$
- 175 °C operating temperature
- Pb-free lead plating

Application

- LED backlighting
- Ideal for high-frequency switching and synchronous rectification

TO-252



Schematic

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
VST25N2000	VST25N2000-T2	TO-252	-	-	-

Absolute Maximum Ratings (T_A=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	250	V
Gate-Source Voltage	V_{GS}	±20	V
Drain Current-Continuous	I_D	15	A
Drain Current-Continuous(T_C=100℃)	I_D (100℃)	10.6	A
Pulsed Drain Current	I_{DM}	60	A
Maximum Power Dissipation	P_D	140	W
Derating factor		0.93	W/℃
Single pulse avalanche energy (Note 1)	E_{AS}	80	mJ
Operating Junction and Storage Temperature Range	T_J,T_{STG}	-55 To 175	℃

Thermal Characteristic

Thermal Résistance, Junction-to-Case	$R_{\theta JC}$	1.1	℃/W

Electrical Characteristics (T_A=25℃unless otherwise noted)

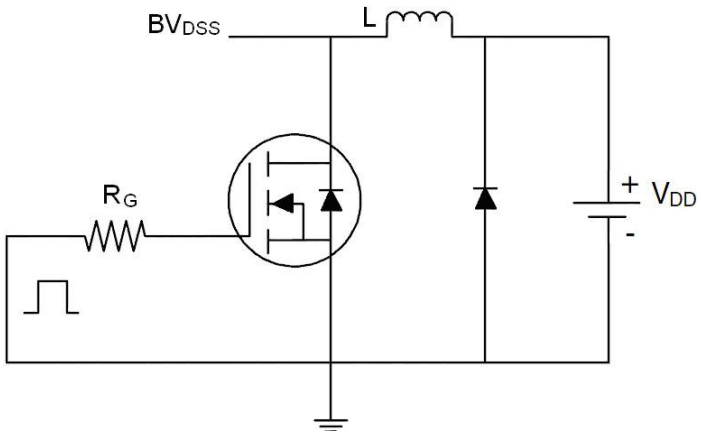
Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS}=0V I_D=250μA	250	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=250V,V_{GS}=0V	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	V_{GS}=±20V,V_{DS}=0V	-	-	±100	nA
On Characteristics						
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS}=V_{GS},I_D=250μA	2.5	3.5	4.5	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	V_{GS}=10V, I_D=7.5A	-	200	250	mΩ
Gate resistance	R_G		-	4.5	-	Ω
Forward Transconductance	g_{FS}	V_{DS}=5V,I_D=15A	15	-	-	S
Dynamic Characteristics						
Input Capacitance	C_{lss}	V_{DS}=125V,V_{GS}=0V, F=1.0MHz	-	475		PF
Output Capacitance	C_{oss}		-	34		PF
Reverse Transfer Capacitance	C_{rss}		-	1.2		PF
Switching Characteristics (Note 2)						
Turn-on Delay Time	$t_{d(on)}$	V_{DD}=125V, R_L=8☒ V_{GS}=10V,R_G=3Ω	-	4	-	nS
Turn-on Rise Time	t_r		-	5	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	10	-	nS
Turn-Off Fall Time	t_f		-	2	-	nS
Total Gate Charge	Q_g	V_{DS}=125V,I_D=15A, V_{GS}=10V	-	8.9	-	nC
Gate-Source Charge	Q_{gs}		-	3.3	-	nC
Gate-Drain Charge	Q_{gd}		-	2.5	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage	V_{SD}	V_{GS}=0V,I_S=15A	-	-	1.2	V
Diode Forward Current	I_S		-	-	15	A
Reverse Recovery Time	t_{rr}	T_J = 25°C, I_F = I_S di/dt = 100A/μs	-	25	-	nS
Reverse Recovery Charge	Qrr		-	110	-	nC

Notes:

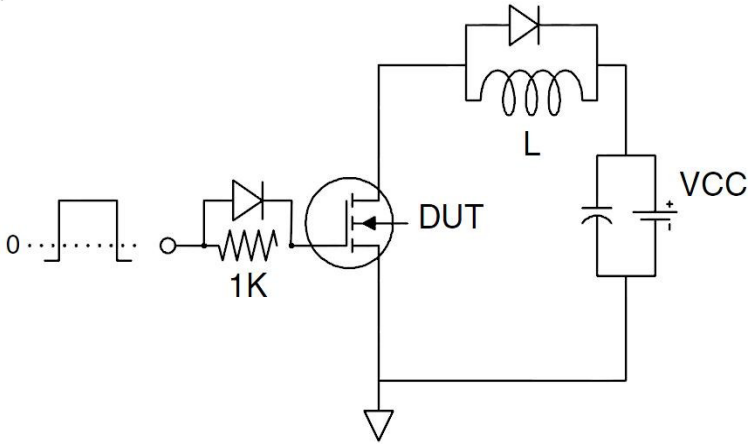
1. EAS condition : Tj=25℃,V_{DD}=50V,V_G=10V,L=0.5mH,Rg=25Ω
2. Guaranteed by design, not subject to production
3. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsin k, assuming a maximum junction temperature of TJ(MAX)=175° C. The SOA curve provides a single pulse rating.

Test Circuit

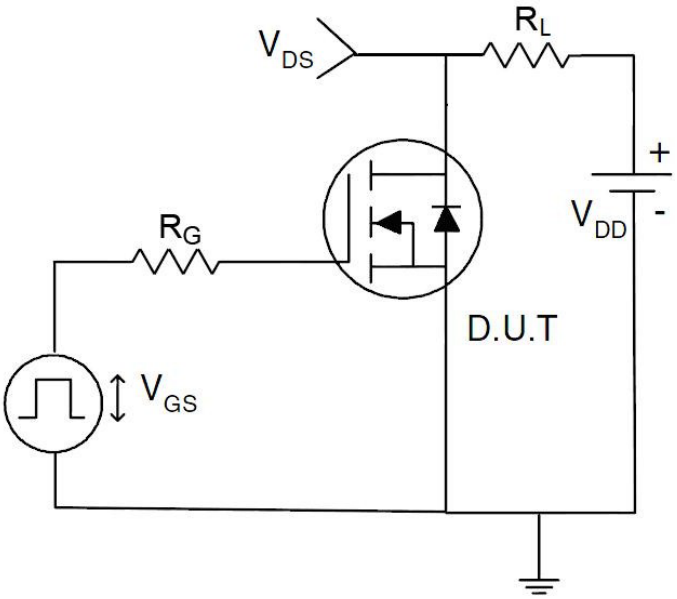
1) E_{AS} test Circuit



2) Gate charge test Circuit



3) Switch Time Test Circuit



Typical Electrical and Thermal Characteristics

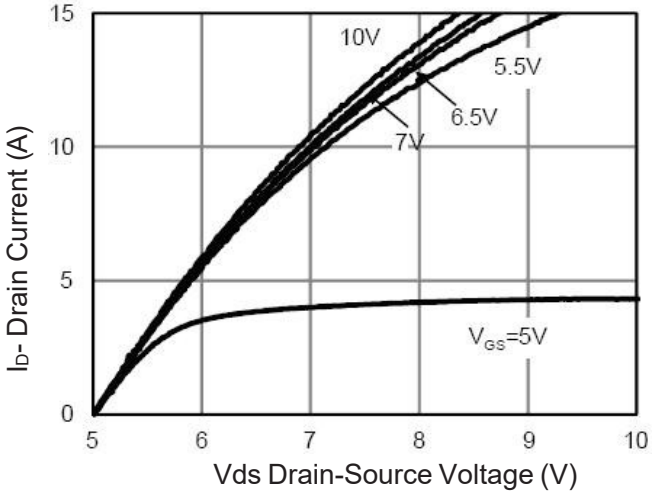


Figure 1 Output Characteristics

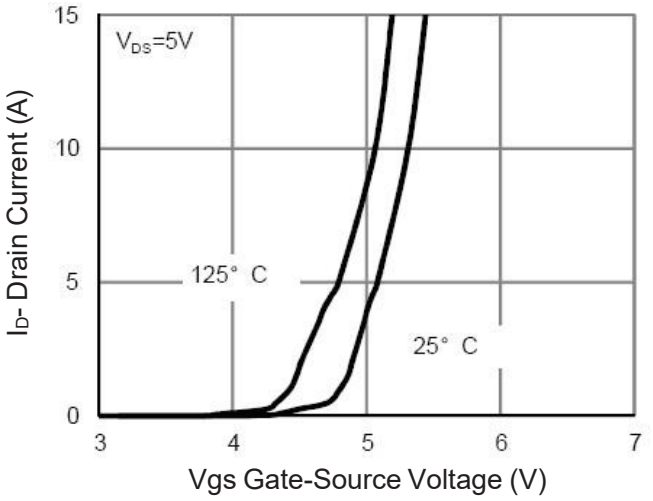


Figure 2 Transfer Characteristics

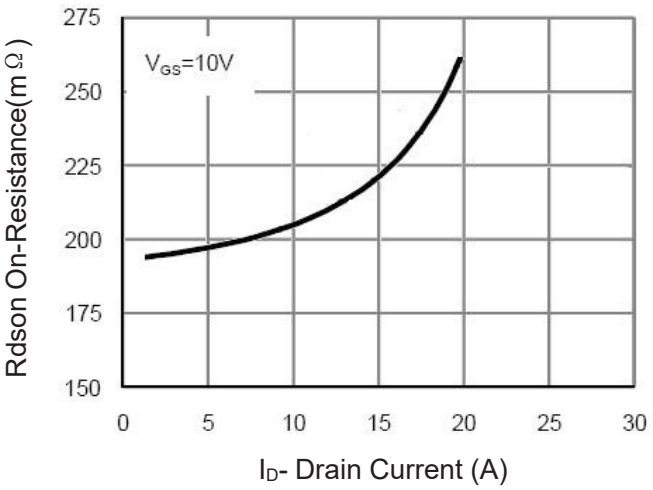


Figure 3 Rdson- Drain Current

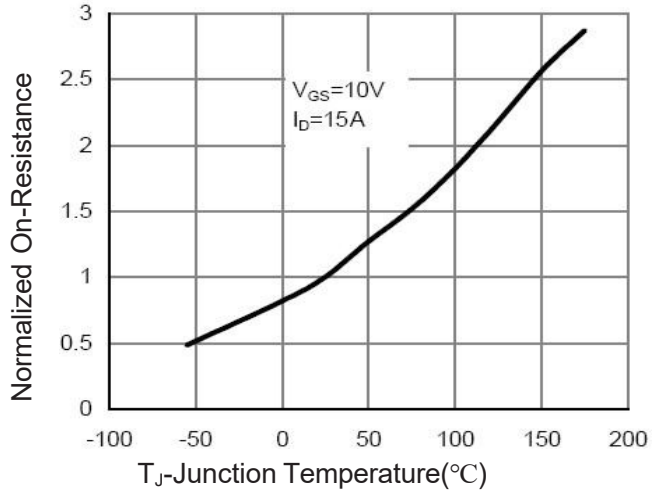


Figure 4 Rdson-Junction Temperature

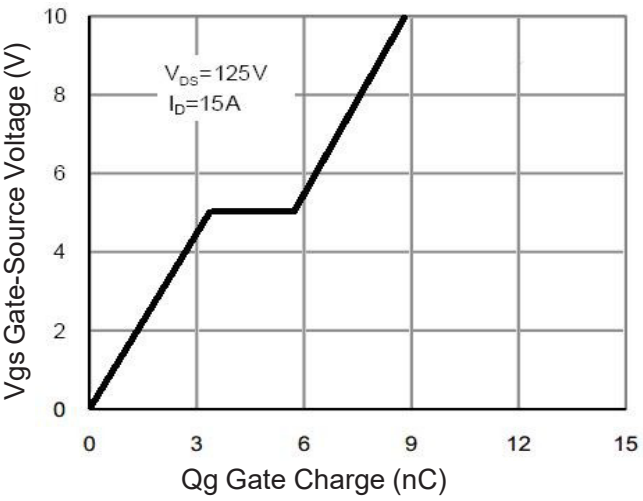


Figure 5 Gate Charge

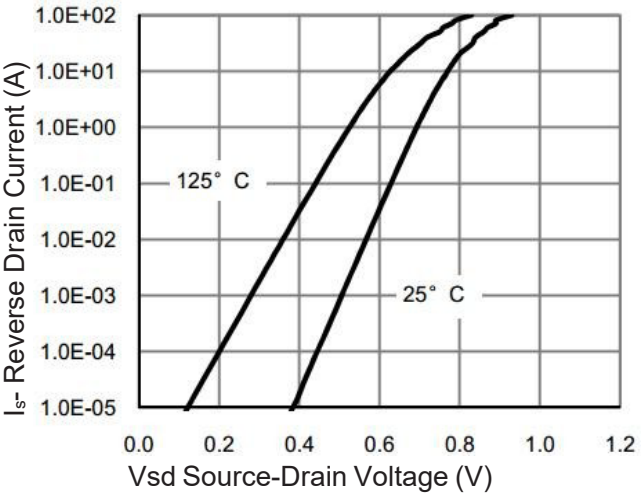


Figure 6 Source- Drain Diode Forward

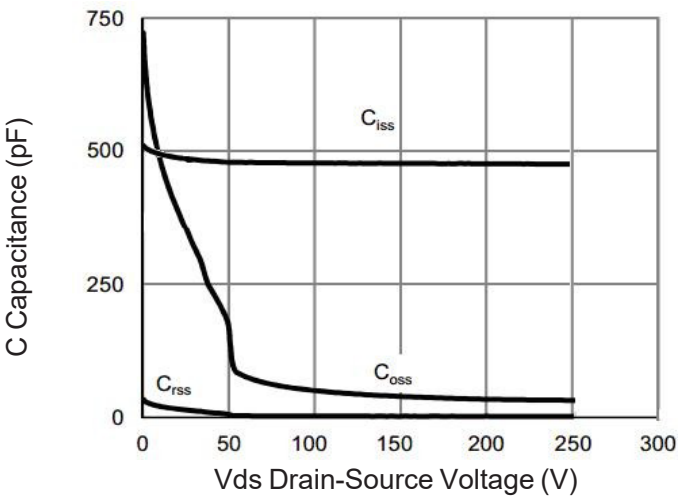


Figure 7 Capacitance vs Vds

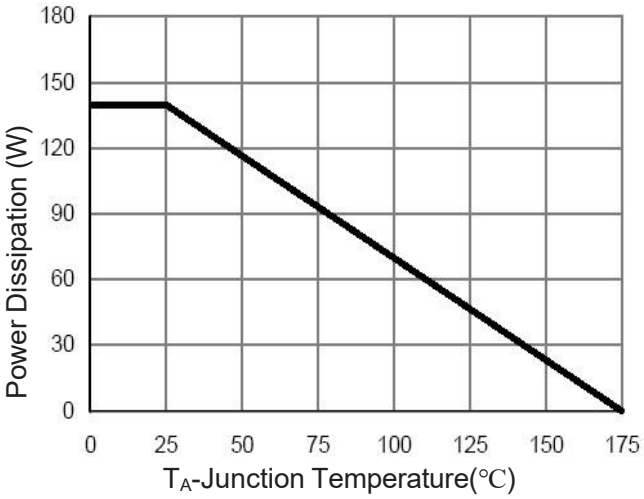


Figure 9 Power De-rating

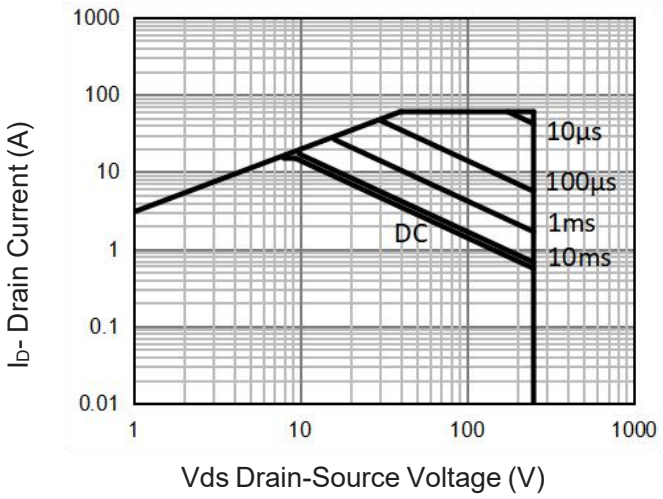


Figure 8 Safe Operation Area (Note 3)

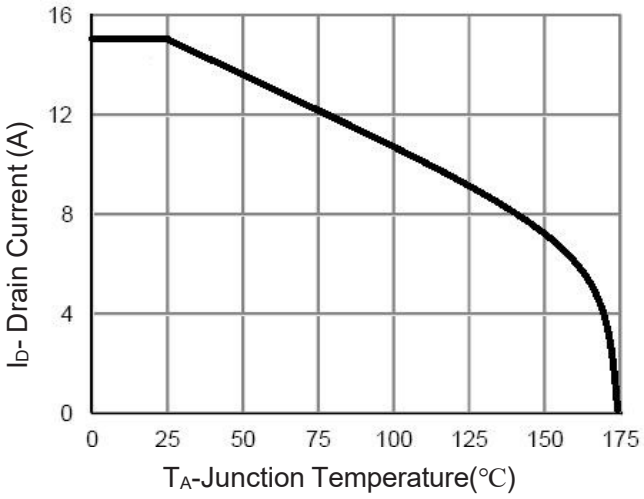


Figure 10 Current De-rating

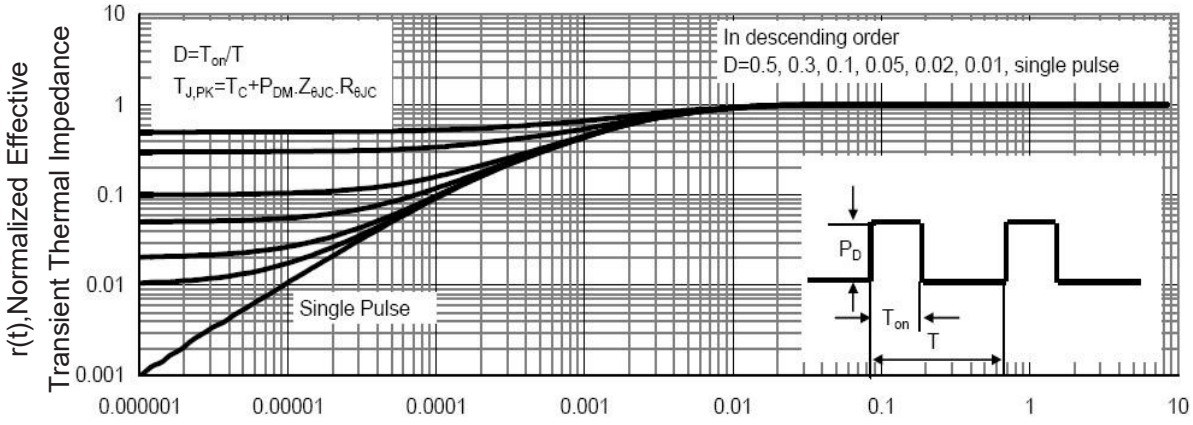


Figure 11 Normalized Maximum Transient Thermal Impedance